

Capabilities

The Amitron Corporation teams of professionally trained CAD/CAM engineers assure a seamless transition of your engineering data to the manufacturing floor. The following information outlines our engineering and manufacturing capabilities.

Process Options:

- Solder mask over bare copper (SMOBC)
- Gold tab plating
- Electroless nickel Immersion gold (ENIG)
- Immersion Silver
- Carbon ink
- Entek Organic Surface Protectant (OSP)
- Immersion tin
- Lead Free Hot Air Solder Level (LF-HASL)
- Solder mask: LPI & Thermal options available
- CNC skip scoring

Data Formats:

- Gerber 274D
- Gerber 274X (imbedded apertures)
- DXF
- PDF
- HPGL
- Auto cad
- ASCII or EIA NC drill files

CAM Capabilities:

- Dual photocircuit plotters
- Valor Genesis software
- Micro-modifications performed with customer approval

- Panel/array optimization available
- Pre-manufacturing design checks on every part
- Artwork generation from bare boards or blueprints
- Net list test fixture generation

PCB Process Capabilities:

Laminate Types:	FR-4 (140Tg, 170Tg, 180Tg) (all UL94V-0 rated), RF and Teflon, Arlon, Getek, Rogers, Nelco and more! Thermal materials including Laird, Arlon, Ventec, Iteq and Chin-Shi, bonded to Aluminum or Copper.
Laminate Thickness:	0.003" to 0.250"
Copper Weight:	½ ounce to 20 ounce, finished
Layer Count:	Single, Double, 3, 4, 6, 8, 10, 12, 14, 16, 18, 20
Line & Space Widths:	0.003"/0.003"

Mechanical Process Tolerances

Minimum annular ring:	.004"
Board edge to edge, routed:	+/- 0.005"
Tooling hole to hole:	+/- 0.002"
Tooling hole to edge:	+/- 0.005"
Holes to copper registration:	+/- 0.003"
Top to bottom registration:	+/- 0.003"
Image line tolerance:	90% art work
Scoring tolerance:	+/- 0.005"
Edge to copper:	+/- 0.008"
Minimum Solder mask clearance:	0.002"
Minimum hole size:	0.008"
Minimum inside radius:	0.012"
Minimum trace width:	0.003"

Pad to pad clearance:	0.007"
Hole diameter: (plated thru)	+/- 0.0025"
Hole diameter: (non-plated up to .250")	+/- 0.001"
Board thickness:	+/- 8%